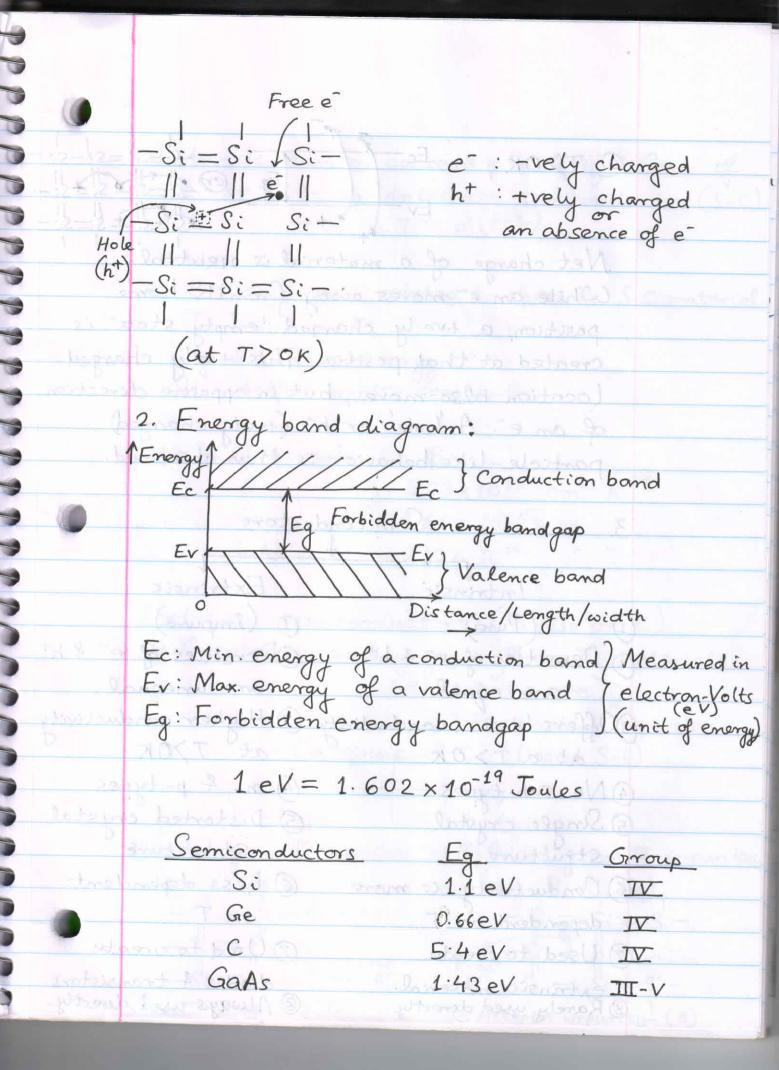
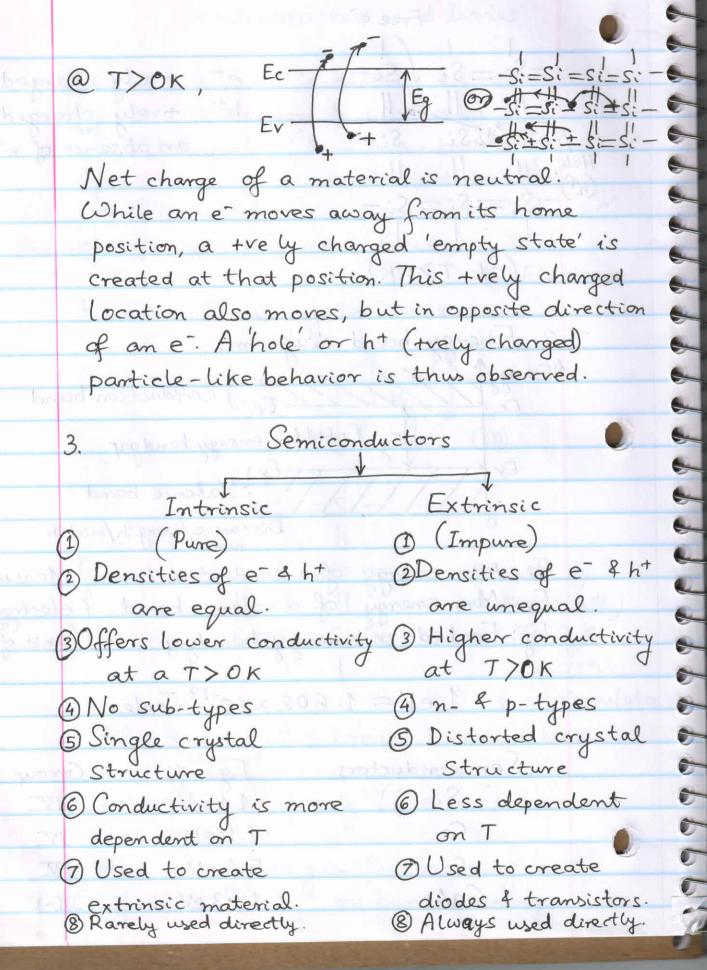
Semiconductors and Diodes

1. Semiconductors - Conductivity in between Conductors & insulators. Valency = 4 (Four outer shell electrons). -ve charged particle. (Simple) > Silicon (Si), Germanium (Ge), Carbon (C) (Compound) - Gallium-Arsenide (Ga-As) III-V e: Electrons Silicon -> Forms crystal matrix -Si = Si = Si -B = 3 / 1 RC 1 1 -Si = Si = Si - (2D with| | | | covalent bonds) -S:=S:=S:- @ T=OK-273°C Si is an insulator T1 > e energy1 > breaks co-valent bond (thermal) energy) ⇒ e- moves freely (free e-) Min. energy to gain for becoming a free e- is Eg or bandgap energy.





Intrinsic carrier concentration (ni): Canc. of e or ht in an intrinsic semiconductors (S-C). $n_i = B. T^{\frac{3}{2}}. e^{\left(\frac{-Eq}{2kT}\right)}$ B: Coefficient related to specific S-C material. T: Temp. in K. Eg: Bandgap energy k: Boltzmann's constant S-C Materials 5.23 x 1015 cm-3 K 1.66 × 1015 2.10 × 10¹⁴ " GaAs Extrinsic semiconductors (Si, Ge or C) Created by adding group II or I materials

Trivalent impurities Pentavalent impurities. Extrinsic S-C (Doped S-C) p-type n-type 1) Added group- I impurities 1) Added group III impurities. (e.g. B, Al, Ga) 2 Donor impurity (P) @ Acceptor impurity (B)

Kelationship between e + ht concentration in a S-C at thormal equilibrium: $n_0.p_0 = n_i^2$ where, no = Thermal equilibrium conc. of e. po = " " h+ n; = Intrinsic carrier conc. > Pentovalent (e.g.P) - n-type At T= 300K, each donor atoms donates free e to the S-C. If, donor, conc. (Nd) >> n; ⇒ no ≅ Nd no. of hte po = $\frac{n_i^2}{Nd}$ (n-type)

(minority)

Also, at T=300K, each acceptor atom accepts a valence e, creating a hole. Majority corriers Acceptor conc. Na >> ni >> po≅ Na $n_0 = \frac{n_i^2}{Na}$ (p-type)

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4. Drift & Diffusion: Basic processes to cause movement of e- & h+ in a S-C.

Lets, understand Current Density first.

J: Amount of current flowing per unit

cross-section area of a material.

Unit of J: A/m²

Drift & Diffusion current densities.

Diffusion current in a S-C is caused by diffusion of charge corriers (e or ht) or concentration gradient inside the material (e.g. Si)

Drift current in a S-C is caused due to external force being exterted (e.g. by electric field) for movement of e or ht.

E-field: Volts (S.I. unit)

Drift:

$$+ \longrightarrow \overline{E}$$
 $- \longrightarrow E$ $-$
 $\overline{V}_{q_n} \leftarrow e^ h^+ \longrightarrow \overline{V}_{q_p}$ $\longrightarrow \overline{J}_{n}$ $\longrightarrow \overline{J}_{p}$

un: Electron mobility $(cm^2/V-s) \cong 1350 \frac{cm^2}{V-s}$ up: Hole mobility $("") \cong 480 \frac{cm^2}{V-s}$ (for low doped Si)

e drift produces drift current density (In) A cm² ht " (Ip) A cm²

$$J_n = -q.n.V_{dn} = +q.n.\mu_n.E$$
; $n=e^-conc.(/cm^3)$
 $J_p = +q.p.V_{dp} = -q.p.\mu_p.E$; $p=h^+conc.(/cm^3)$

Conductivity (O) [= cm] σ= q.n.μη + q.p.μρ. In n-type S-C: n>>p
" p-type S-C: p>>n Diffusion: Causes flow of particles from a region of high conc. to a region of low conc.

lower higher lower higher ht 1

e conc. process conc. e diffusion
I-density $J_n = q. D_n. \frac{dn}{dx}$ $J_p = -q. D_p. \frac{dp}{dx}$ dn: Gradient of dp: Gradient of ht conc. e conc. Dn: e- diffusion coefficient Excess carriers: e or ht e-h+ pairs are produced in a s-c while an external energy is applied (e.g. light). $n = n_0 + \delta n$ b = po + Sp Excess carriers (only for a time)

At thermal equilibrium

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